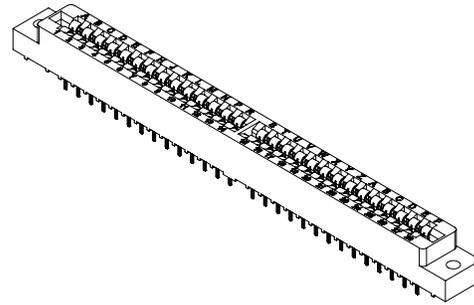




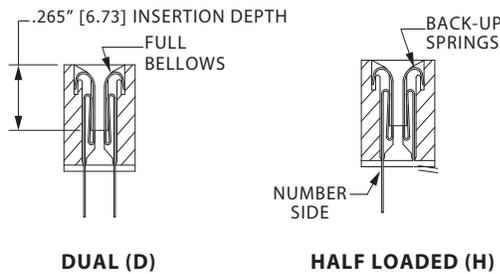
.156" [3.96 mm] Contact Centers, .431" [10.95 mm] Insulator Height, Special Body Configuration Dip Solder/Eyelet/Right Angle

SPECIFICATIONS

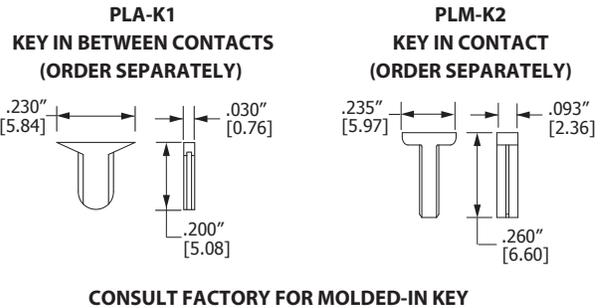
- Accommodates .062" ± .008" [1.57 mm ± 0.20 mm] PC board
- Molded-in key available
- 3 Amps current rating for one contact energized (for 5 Amps application, consult factory)
- 30 milli Ohms maximum at rated current
- UL Flammability Rating: 94V-0



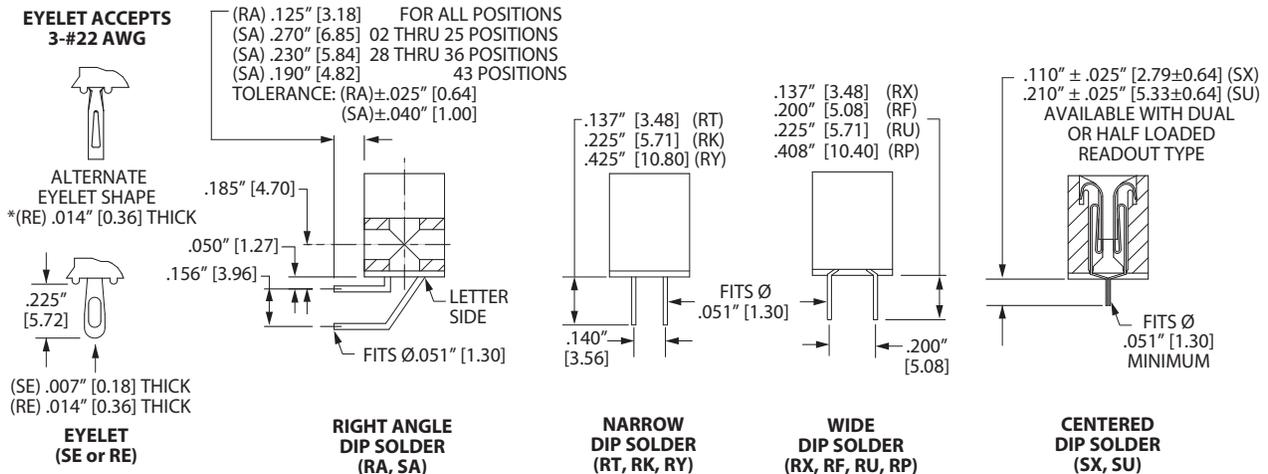
READOUT



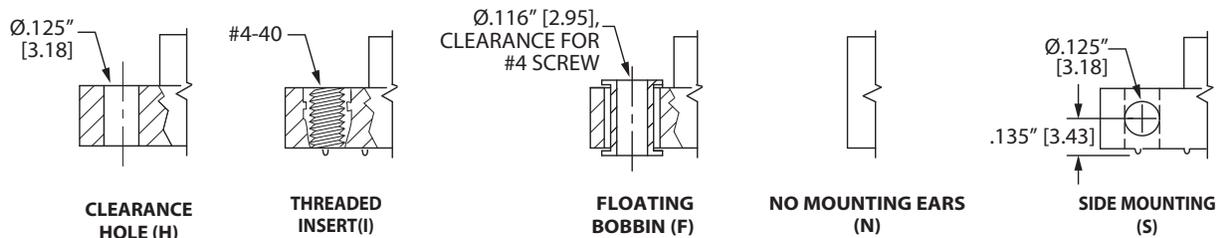
POLARIZING KEY



TERMINATION TYPE



MOUNTING STYLE



* Beryllium Copper & Beryllium Nickel (H, A, J, F, C & W Material Codes) Only.



.156" [3.96 mm] Contact Centers, .431" [10.95 mm] Insulator Height, Special Body Configuration Dip Solder/Eyelet/Right Angle

PART NUMBER OPTIONS

E B M 43 D RT H - S37

MATERIALS (INSULATOR/CONTACT)

- E = PBT/Phosphor Bronze (Standard)
- R = PPS/Phosphor Bronze
- G = PA9T/Phosphor Bronze
- H = PBT/Beryllium Copper
- A = PPS/Beryllium Copper
- J = PA9T/Beryllium Copper
- *F = PPS/Spinodal (Overall Gold Plating Only)
- *C = PPS/Beryllium Nickel (Overall Gold Plating Only)
- *W = PEEK/Beryllium Nickel (Overall Gold Plating Only)

Consult Factory for Special Soldering Guidelines
 *Consult factory for availability.
 Refer to Page 7 for Operating/Processing Temperatures

CONTACT FINISH - RoHS Compliant

All platings are Lead Free and have .000050" Nickel underplate

Contact Surface	Termination
B = .000010" Gold	.000100" Pure Tin, Matte
C = .000030" Gold	.000100" Pure Tin, Matte
G = .000010" Gold	.000005" Gold
Y = .000030" Gold	.000005" Gold
Contact Surface	Overall Plating
S = .000010" Gold	.000010" Gold
M = .000030" Gold	.000010" Gold
E = .000100" Pure Tin, Matte	.000100" Pure Tin, Matte

CONTACT CENTERS

M = .156" [3.96 mm]

NUMBER OF CONTACT POSITIONS

28 (14/14), 36 or 43

MODIFICATION CODE (Consult Factory)

- S37 = Reverse Contact ID & Shorter Card Slot Length
- S92 = Center Barrier Molded in Card Slot

MOUNTING STYLE (Opposite Page)

- H = .125" [3.18 mm] Clearance Holes
- N = No Mounting
- S = Side Mounting
- I = Threaded Inserts
- F = Floating Bobbin

TERMINATION TYPE (Opposite Page)

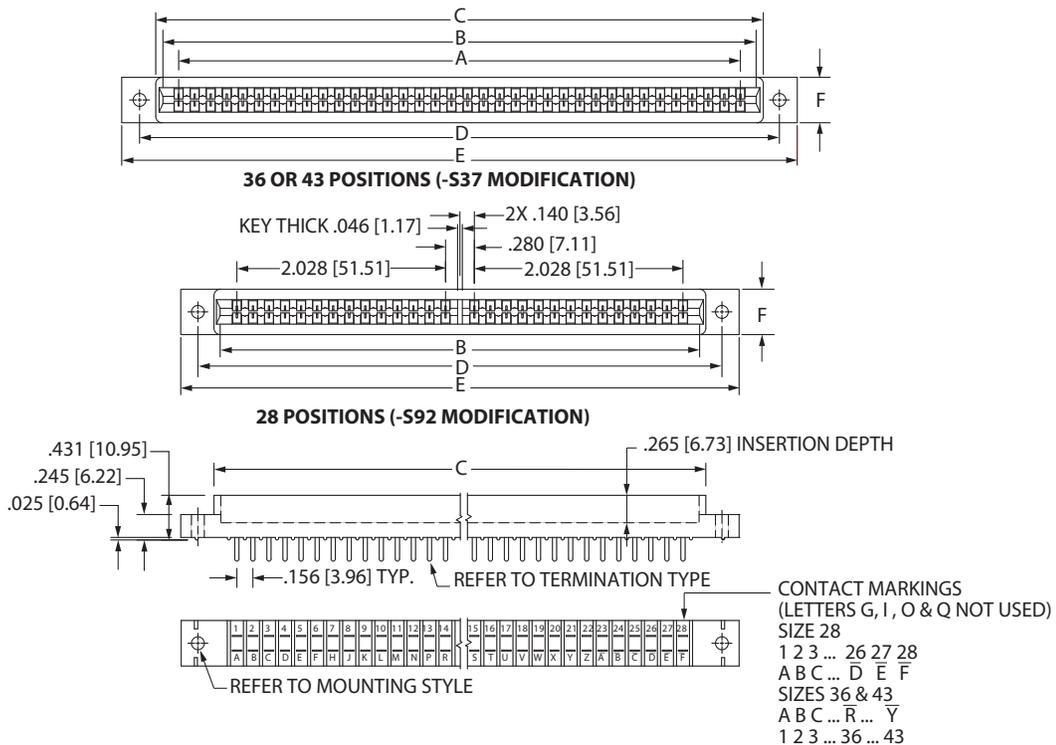
- RA = .125" [3.18 mm] Right Angle Dip Solder
- SA = Long Right Angle Dip Solder
- RT = .140" X .137" [3.56 mm X 3.48 mm] Dip Solder
- RK = .140" X .225" [3.56 mm X 5.72 mm] Dip Solder
- RY = .140" X .425" [3.56 mm X 10.80 mm] Dip Solder
- RX = .200" X .137" [5.08 mm X 3.48 mm] Dip Solder
- RF = .200" X .200" [5.08 mm X 5.08 mm] Dip Solder
- RU = .200" X .225" [5.08 mm X 5.72 mm] Dip Solder
- RP = .200" X .408" [5.08 mm X 10.36 mm] Dip Solder
- SX = .110" [2.79 mm] Centered Dip Solder
- SU = .210" [5.33 mm] Centered Dip Solder
- SE = .007" [0.18 mm] Thick Eyelet
- RE = .014" [0.36 mm] Thick Eyelet

READOUT (Opposite Page)

- D = Dual
- D = Dual Row/ Crimp to Center for Single Readout (SX, SU Termination Only)
- H = Half Loaded

DIMENSIONS

Dimensions in [] are in millimeters, all others are in inches.



Tolerances on non-critical dimensions may vary slightly due to shrinkage differential per insulator material; Consult factory.

POSITIONS/ CONTACTS	INCHES						MILLIMETERS						CENTER BARRIER
	A±.008	B±.008	C±.015	D±.010	E MAX	F+.005/ -.015	A±0.20	B±0.20	C±0.38	D±0.25	E MAX	F+0.13/ -0.38	
28/56		4.660	4.780	5.093	5.427	0.438		118.36	121.41	129.36	137.85	11.13	YES
36/72	5.460	5.766	5.906	6.219	6.566	0.438	138.68	146.46	150.01	157.96	166.78	11.13	NO
43/86	6.552	6.810	7.000	7.302	7.643	0.500	166.42	172.97	177.80	185.47	194.13	12.70	NO